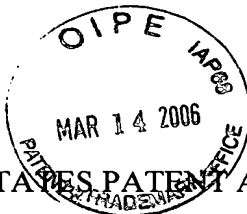


DOCKET NO.: 268844US0PCT



IFW

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

GROUP: 3723

Hiroshi SHIHO, et al.

SERIAL NO: 10/529,742

ATTENTION:
FILING RECEIPT CORRECTIONS

FILED: January 6, 2006

FOR: POLISHING PAD FOR SEMICONDUCTOR WAFER, POLISHING
MULTILAYERED BODY FOR SEMICONDUCTOR WAFER HAVING
SAME, AND METHOD FOR POLISHING SEMICONDUCTOR WAFER

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

Office of Initial Patent Examination
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The Patent Office is requested to provide a corrected Official Filing Receipt for the following.

PLEASE NOTE THAT THE 3RD APPLICANT'S NAME IS INCORRECT. IT SHOULD READ AS FOLLOWS:

HIROSHI SHIHO, TOKYO, JAPAN

YUKIO HOSAKA, TOKYO, JAPAN

KOU HASEGAWA, TOKYO, JAPAN

NOBUO KAWAHASHI, TOKYO, JAPAN

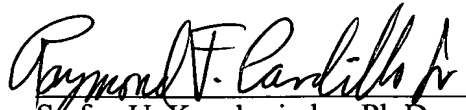
PLEASE NOTE THAT THE TITLE IS INCORRECT. IT SHOULD READ AS FOLLOWS:

POLISHING PAD FOR SEMICONDUCTOR WAFER, **POLISHING MULTILAYERED**
BODY FOR SEMICONDUCTOR WAFER **HAVING SAME, AND** METHOD FOR
POLISHING SEMICONDUCTOR WAFER

No fees are required. If you have any questions, please do not hesitate to contact us.

Respectfully Submitted,

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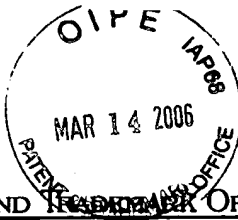
(OSMMN 08/05)

DOCKET NO.: 268844US0PCT

SERIAL NO: 10/529,742



UNITED STATES PATENT AND TRADEMARK OFFICE



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| APPL NO. | FILING OR 371 (c) DATE | ART UNIT | FIL FEE REC'D | ATTY. DOCKET NO | DRAWINGS | TOT CLMS | IND CLMS |
|------------|---------------------------|----------|---------------|-------------------|----------|----------|----------|
| 10/529,742 | 01/06/2006 | 3723 | 900 | 268844US2PCT 0 | 9 | 17 | 3 |

CONFIRMATION NO. 8533

22850
 OBLON, SPIVAK, MCCLELLAND, MAIER & NEUSTADT, P.C.
 1940 DUKE STREET
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FILING RECEIPT



OC000000018111648

Date Mailed: 02/23/2006

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. **If an error is noted on this Filing Receipt, please mail to the Commissioner for Patents P.O. Box 1450 Alexandria Va 22313-1450. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).**

Applicant(s)

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Assignment For Published Patent Application

JSR Corporation, Tokyo, JAPAN

Power of Attorney: The patent practitioners associated with Customer Number 22850.

Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP04/05963 04/23/2004

Foreign Applications

Projected Publication Date: 06/01/2006

Non-Publication Request: No

Early Publication Request: No

Title

RECEIVED: 3/2/06
 OBLON, SPIVAK, MCCLELLAND
 MAIER & NEUSTADT, P.C.
 DOCKETING DEPT.
 Initials/Date Docketed: CTP 3/2/06
 Type of Resp(s): _____
 Due Date(s): _____

~~POLISHING MULTILAYERED BODY FOR~~
 Polishing pad for semiconductor wafer, and laminated body for polishing of semiconductor wafer
~~equipped with the same as well as method for polishing of semiconductor wafer~~
 HAVING SAME, AND

Preliminary Class

451

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